

Dark current simulation and verification of $\text{In}_{0.83}\text{Ga}_{0.17}\text{As}$ detector with superlattice electron barrier

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Abstract: To obtain the dark current mechanism of $\text{In}_{0.83}\text{Ga}_{0.17}\text{As}$ detector, TCAD software was used to simulate its dark current property. The detectors include two structures with and without the super lattice (SL) electronic barrier in the InGaAs absorbed layer. At the same time, the detector has been fabricated to verify the simulation results. The results show that SL barrier can adjust the energy band structure and change the transport property of the carriers, and thus suppress the SRH recombination and decrease the dark current. Simulation results are in good agreement with experimental results. The influence of the location and periods of SL barrier on dark current was also simulated. The SL electronic barrier structure was optimized.

Key words: $\text{In}_{0.83}\text{Ga}_{0.17}\text{As}$ detector, super lattice(SL) electronic barrier, dark current, TCAD simulation

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含有超晶格电子势垒的 $\text{In}_{0.83}\text{Ga}_{0.17}\text{As}$ 探测器暗电流仿真和验证

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摘要: 为了获得 $\text{In}_{0.83}\text{Ga}_{0.17}\text{As}$ 探测器的暗电流机制, 采用了 TCAD 软件对吸收层中含有和不含超晶格电子势垒的 p-i-n 结构探测器暗电流特性进行仿真, 并开展了器件验证. 结果表明, 超晶格势垒可以调整器件的能带结构, 改变载流子传输特性, 降低 SRH 复合, 从而降低器件的暗电流, 仿真结果与实验结果吻合. 在此基础上, 分析了势垒位置和周期变化对暗电流的影响, 提出了进一步降低器件暗电流的超晶格电子势垒优化结构.

关键词: $\text{In}_{0.83}\text{Ga}_{0.17}\text{As}$ 探测器; 超晶格电子势垒; 暗电流; TCAD 仿真

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Introduction

Short-wavelength infrared (SWIR) InGaAs detectors has been applied in various fields, such as astronomical observation, earth detection and machine vision^[1-2]. Detectors of In_{0.53}Ga_{0.47}As with lattice matched with InP has a 1.7 μm cut-off wavelength at room temperature. However, in the remote sensing field, 1-2.5 μm is much more important wavelength range, which requires indium composition to be increased to 0.83. The In_{0.83}Ga_{0.17}As detector has more defects due to its mismatch to the InP substrate. Besides, some groups showed that InAs/GaSb super lattice (SL) can be used in the mid-wavelength and long-wavelength infrared detectors to decrease the dark current^[3-4], and InAs/InGaAs was also used to decrease the dark current in the SWIR InGaAs detector^[5]. The dark current of the In_{0.83}Ga_{0.17}As detectors has been decreased to about 1 nA/cm² at low temperature^[6-7]. However, few papers analyzed the dark current mechanism of the In_{0.83}Ga_{0.17}As detector with and without SL. There are few reported works for simulating and optimizing the structure of the detectors.

In this paper, technology computer aided design (TCAD) software was used to simulate the dark current of the In_{0.83}Ga_{0.17}As detector based on theoretical model. By TCAD, two kinds of structure detectors with and without SL in the absorbed layer were simulated. At the same time, the detectors were also fabricated. Its current-voltage curves were measured by the Agilent B1500A Semiconductor Device Analyzer at room temperature (RT) and low temperature (LT). In addition, further optimization was simulated for different locations and periods of SL barrier.

1 Dark current theory of In_{0.83}Ga_{0.17}As detector

The dark current of p-i-n detectors includes several distinct mechanisms, diffusion, generation recombination, trap-assisted tunneling (TAT) effect and so on. At room temperature, the dark current is limited by the diffusion process^[5]. When the temperature falls, generation recombination mechanism dominated the dark current. As for generation recombination, Shockley-Hall-Read (SRH) mechanism, instead of the Auger recombination, plays the main role at low reverse bias or zero-bias because the carriers concentration of depletion region is very low at low reverse bias or zero-bias. In addition, the TAT current is the important component at low temperature^[8-9].

The main dark currents in the In_{0.53}Ga_{0.47}As/InP near-infrared detector are the diffusion current and SRH generation-recombination current at room temperature and low temperature^[10], respectively. However, for the In_{0.83}Ga_{0.17}As on the InP substrate, there are many defects caused by the lattice mismatch, and the defects form the trap levels in the In_{0.83}Ga_{0.17}As absorption layer. TAT can occur depending on the trap levels. Therefore, TAT mechanism should be considered in the dark current model of In_{0.83}Ga_{0.17}As SWIR detector^[11-12]. And

the In_{0.83}Ga_{0.17}As SWIR detector works at low bias, so the main mechanism of the dark current should be diffusion current, SRH current and TAT current. The dark current model can be expressed as

$$I_{\text{TOTAL}} = I_{\text{DIFF}} + I_{\text{SRH}} + I_{\text{TAT}} \quad (1)$$

The dark current model of In_{0.83}Ga_{0.17}As detector in Ref. [13] reveals that the main components are diffusion and SRH current mechanism at zero-bias and room temperature. When the temperature becomes lower, the SRH current is suppressed and the TAT current becomes dominant. It is because that the energy gap becomes narrow and the tunneling effect happens easily at low temperature.

For the SRH generation recombination^[14-15],

$$R_{\text{SRH}} = \frac{N_T(pn - n_i^2)}{\tau_{p0} \left[n + n_i \exp\left(\frac{E_i - E_T}{kT}\right) \right] + \tau_{n0} \left[p + n_i \exp\left(\frac{E_T - E_i}{kT}\right) \right]} \quad (2)$$

where τ_{p0} is the minority carrier lifetime due to SRH processes and τ_{n0} is the lifetime of electrons; n_i and E_i are the intrinsic carrier concentration and intrinsic Fermi level; E_T and N_T are the trap level and defects trap concentrations, p and n are the hole and electron concentrations, respectively.

2 Results and discussion

There are two kinds of structure, S_1 and S_2 , used for simulating the current-voltage property of the detector. This is typical p-i-n structure of the SWIR In_{0.83}Ga_{0.17}As detector, and the insets of Figs. 1(a) and (b) show the structure of the detectors in the simulation. The thickness of the P⁺-In_{0.83}Al_{0.17}As layer is 530 nm with indium component 0.83, and the density of hole is 6×10^{18} cm⁻³. The thickness of i-In_{0.83}Ga_{0.17}As layer is 1500 nm, and its density of electrons is 5×10^{16} cm⁻³. The thickness of the N⁺-In_xAl_{1-x}As layer is about 1900 nm, and the component of indium x varies from 0.52 to 0.87.

Figure 1(a) and (b) are the energy band diagrams of S_1 and S_2 structure. The SL is inserted into the In_{0.83}Ga_{0.17}As absorbed layer to improve the performance. After inserting the SL in the InGaAs absorbed layer, the energy band has some changes. Figure 2(a) is the In_{0.66}Ga_{0.34}As/InAs super lattice structure. With the help of the TCAD, their energy band diagrams can be obtained, as shown in Fig. 2(b). It has the same ten periods of In_{0.66}Ga_{0.34}As/InAs with a thickness of 10 nm for each period. The In_{0.66}Ga_{0.34}As/InAs super lattice is a good choice. The lattice constant of In_{0.66}Ga_{0.34}As is smaller than that of In_{0.83}Ga_{0.17}As, while the lattice constant of InAs is bigger than that of In_{0.83}Ga_{0.17}As. In the SL structure, both In_{0.66}Ga_{0.34}As and InAs have the same thickness, so the In_{0.66}Ga_{0.34}As/InAs SL layers have strain-compensated effect on the In_{0.83}Ga_{0.17}As absorbed layer. The epitaxial layer was grown by gas source molecular beam epitaxy (GSMBE). By inserting SL barrier, the quality of the In_{0.83}Ga_{0.17}As layer becomes better^[5,16].

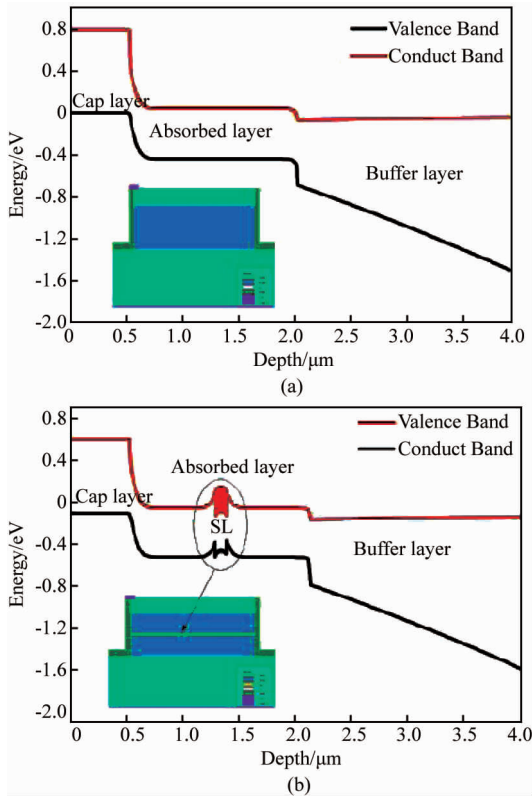


Fig. 1 Energy band of structure S_1 (a) and structure S_2 (b). The inserts illustrate the corresponding structures 图 1 (a) S_1 结构的能带图, (b) S_2 结构的能带图; 内插图是对应的结构

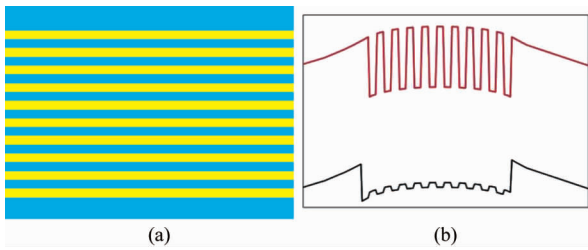


Fig. 2 (a) Super lattice barrier structure, (b) SL's energy band graph 图 2 (a) 超晶格势垒结构, (b) 超晶格结构的能带图

Based on the S_1 and S_2 structures as shown in Fig. 1, two kinds of detectors, D_1 and D_2 , were fabricated respectively, as shown in Fig. 3. In addition, the lattice constant of $In_{0.52}Al_{0.47}As$ matches to the InP substrate. The carrier concentration is about $4 \times 10^{18} \text{ cm}^{-3}$. For the D_2 , the thickness of the SL barrier in the middle of the absorbed layer is $0.1 \mu\text{m}$. The simulation and experimental results of D_1 and D_2 are shown in Fig. 4. It is obvious that the dark current of D_2 decreases much than that of the traditional p-i-n structure detector D_1 . The experimental and simulation results comply well at low bias, which verifies the feasibility of the TCAD model^[17].

At room temperature, dark current at reverse bias is flat, which indicates that the current component mainly includes diffusion and SRH current. At -0.01 V , the ex-

perimental current density of D_1 is $8.27 \times 10^{-4} \text{ A/cm}^2$ and simulation is $5.20 \times 10^{-4} \text{ A/cm}^2$, while experimental current density of D_2 is $3.25 \times 10^{-4} \text{ A/cm}^2$ and simulation is $1.87 \times 10^{-4} \text{ A/cm}^2$, respectively. The current decreases to half of the original one after inserting the SL barrier. This is because that the barrier blocks the electrons recombination in the conduction band, that is to say the SRH recombination lifetime becomes longer so that the barrier can decrease the SRH current.

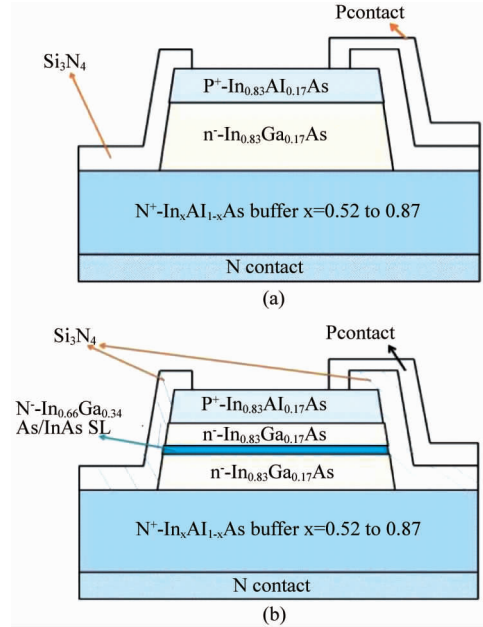


Fig. 3 (a) S_1 is the normal p-i-n structure, (b) S_2 is inserted SL electronic barrier in the absorbed layer 图 3 (a) S_1 结构是常规的 p-i-n 结构, (b) S_2 结构是在吸收层中插入超晶格电子势垒

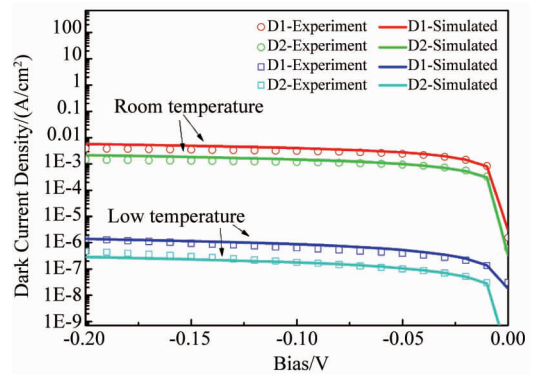


Fig. 4 J - V experiment and simulation curves of D_1 and D_2 at room temperature and low temperature 图 4 器件 D_1 和 D_2 在室温和低温下的 J - V 实验和仿真拟合曲线

From the results of Fig. 4 at low temperature, it is obvious that the current components have been changed. At zero-bias, the dark current decreases larger than that at a relatively big reverse bias. The reason is that the current has been dominant by the TAT current which is suppressed by the barrier at low temperature.

Table 1 Dark current density at -0.01 V under room temperature**表 1** 室温下在 -0.01 V 偏压的暗电流密度

Bias /V	D ₁ - Experiment	D ₂ - Experiment	D ₁ - Simulation	D ₂ - Simulation
Jd@-0.01	$8.27 \times 10^{-4}\text{ A/cm}^2$	$3.25 \times 10^{-4}\text{ A/cm}^2$	$5.20 \times 10^{-4}\text{ A/cm}^2$	$1.87 \times 10^{-4}\text{ A/cm}^2$

Table 2 Dark current density at -0.01 V under low temperature**表 2** 低温下在 -0.01 V 偏压的暗电流密度

Bias /V	D ₁ - Experiment	D ₂ - Experiment	D ₁ - Simulation	D ₂ - Simulation
Jd@-0.01	$1.34 \times 10^{-7}\text{ A/cm}^2$	$2.98 \times 10^{-8}\text{ A/cm}^2$	$1.17 \times 10^{-7}\text{ A/cm}^2$	$2.55 \times 10^{-8}\text{ A/cm}^2$

Above results proves that being inserted into the In-GaAs absorbed layer, $\text{InAs}/\text{In}_{0.66}\text{Ga}_{0.34}\text{As}$ super lattice can decrease the dark current. Because the doping is the same, it formed the isotype heterojunction in their interface^[18-19]. So its energy band graph has apparent changes. As shown in Fig. 2(b), conduction band has bigger barrier height than the valence band. This structure can change the carriers transport and form the electron barrier to block the electron in the conduction band. However, the hole carrier transport in the valence band. The barrier in the valence band is so small that the hole carrier can pass through barrier easily, so that the SL barrier has little effect for the photo response which depends on the hole carrier transport.

Location and period optimization of the electronic barrier was also studied. It is obvious that the SL barrier can adjust the energy band as shown in Fig. 2, so the location and period optimization should be taken into account.

We designed the simulation which used different distance from the location of the SL to interface between the cap layer and absorption layer, and named L_1 , L_2 , L_3 . As shown in Table 3, L_1 is close to the depletion region, L_2 is close to the middle location of the absorbed layer and L_3 is close to the substrate. The simulation results are shown in Fig. 5(a). The results indicate that dark current first decreases and then increases with the increase of distance. The barrier can not only suppress the mismatch defects from the substrate, but also block the electron transporting to the depletion region for suppressing the electron current. When the location is on L_2 , the interaction of two kinds can guarantee the dark current lower than that of L_1 and L_3 . The thickness in one period was chosen as 5 nm, 10 nm, 15 nm or 20 nm. The results reveal that 15 nm is the better choice as shown in Fig. 5(b). When the period thickness is too thin, the barrier will be narrow and the tunneling will happen so that electrons can pass SL barrier. However the period is 15 nm, the barrier can block the electron current well. However the period is up to 20 nm, the barrier becomes wide so that the electrons can accumulate at the barrier well. Finally, the electric field enhancement can help the electron pass through the barrier.

Table 3 Different location of SL**表 3** 超晶格的不同位置

	L_1	L_2	L_3
Location	1.1 μm	1.4 μm	1.6 μm

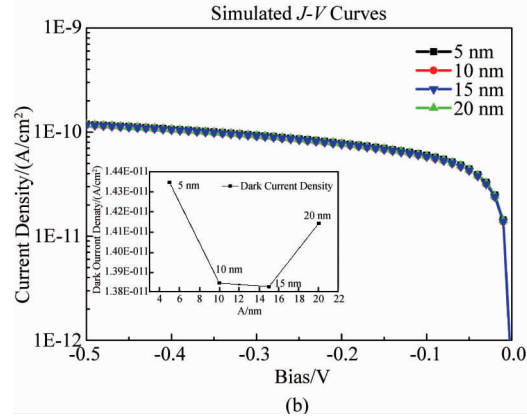
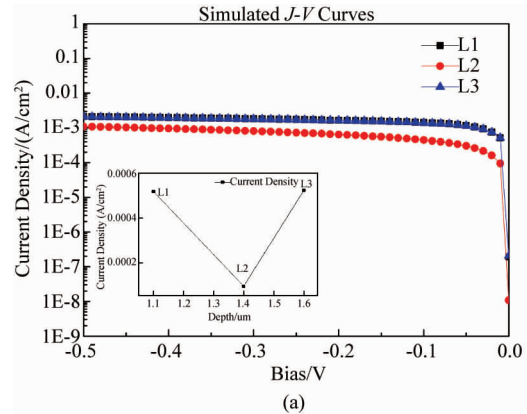


Fig. 5 J - V curves of different barrier locations and periods
图 5 超晶格势垒不同位置和周期的 J - V 曲线,内插图是在 -0.01 V 下的暗电流密度

3 Conclusion

In summary, we have studied dark current of $\text{In}_{0.83}\text{Ga}_{0.17}\text{As}$ detector with simulation and experimental method. It was found that the dark current can be suppressed effectively both at room temperature and low temperature by inserting $\text{In}_{0.66}\text{Ga}_{0.34}\text{As}/\text{InAs}$ SL electronic barrier. In addition, the location and period of SL barrier can also affect the dark current. The dark current is low when the SL barrier with a period thickness of 15 nm is close to the middle location of the absorbed layer. The results are very useful for designing and obtaining detector with low dark current.

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